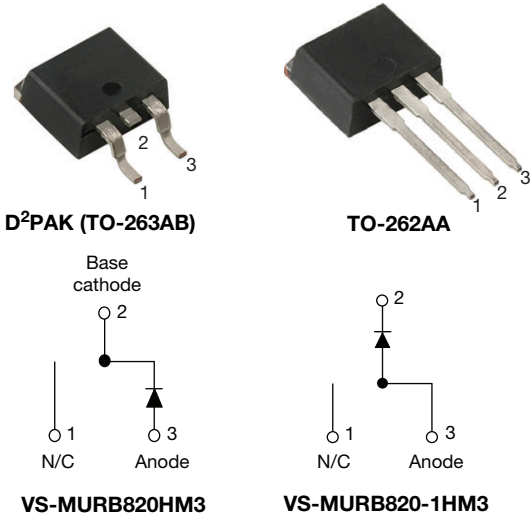


## Ultrafast Rectifier, 8 A FRED Pt<sup>®</sup>



### FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified, meets JESD-201 class 1A thin whisker test
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### DESCRIPTION / APPLICATIONS

MUR.. series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

### MECHANICAL DATA

**Case:** D<sup>2</sup>PAK (TO-263AB), TO-262AA

Molding compound meets UL 94 V-0 flammability rating

**Terminals:** matte tin plated leads, solderable per J-STD-002

### LINKS TO ADDITIONAL RESOURCES



| PRIMARY CHARACTERISTICS |   |
|-------------------------|---|
| $I_{F(AV)}$             | 8 A                                     |
| $V_R$                   | 200 V                                   |
| $V_F$ at $I_F$          | 0.75 V                                  |
| $t_{rr}$                | 35 ns                                   |
| $T_J$ max.              | 175 °C                                  |
| Package                 | D <sup>2</sup> PAK (TO-263AB), TO-262AA |
| Circuit configuration   | Single                                  |

| ABSOLUTE MAXIMUM RATINGS                    |                |   |             |       |
|---|----------------|---|-------------|-------|
| PARAMETER                                   | SYMBOL         | TEST CONDITIONS                                   | MAX.        | UNITS |
| Peak repetitive reverse voltage             | $V_{RRM}$      |   | 200         | V     |
| Average rectified forward current           | $I_{F(AV)}$    | Total device, rated $V_R$ , $T_C = 150$ °C        | 8           | A     |
| Non-repetitive peak surge current           | $I_{FSM}$      |   | 100         |       |
| Peak repetitive forward current             | $I_{FM}$       | Rated $V_R$ , square wave, 20 kHz, $T_C = 150$ °C | 16          |       |
| Operating junction and storage temperatures | $T_J, T_{Stg}$ |   | -55 to +175 | °C    |

| ELECTRICAL SPECIFICATIONS ( $T_J = 25$ °C unless otherwise specified) |               |  |      |      |       |         |
|---|---------------|--|------|------|-------|---------|
| PARAMETER   | SYMBOL        | TEST CONDITIONS                              | MIN. | TYP. | MAX.  | UNITS   |
| Breakdown voltage, blocking voltage                                   | $V_{BR}, V_R$ | $I_R = 100$ $\mu$ A                          | 200  | -    | -     | V       |
| Forward voltage   | $V_F$         | $I_F = 8$ A                                  | -    | 0.92 | 0.975 |         |
|   |               | $I_F = 8$ A, $T_J = 150$ °C                  | -    | 0.75 | 0.895 |         |
| Reverse leakage current   | $I_R$         | $V_R = V_R$ rated                            | -    | -    | 5     | $\mu$ A |
|   |               | $T_J = 150$ °C, $V_R = V_R$ rated            | -    | -    | 250   |         |
| Junction capacitance  | $C_T$         | $V_R = 200$ V                                | -    | 25   | -     | pF      |
| Series inductance   | $L_S$         | Measured lead to lead 5 mm from package body | -    | 8.0  | -     | nH      |



| DYNAMIC RECOVERY CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified) |                  |  |      |      |      |       |
|--|------------------|--|------|------|------|-------|
| PARAMETER  | SYMBOL           | TEST CONDITIONS  | MIN. | TYP. | MAX. | UNITS |
| Reverse recovery time  | t <sub>rr</sub>  | I <sub>F</sub> = 1.0 A, dI <sub>F</sub> /dt = 50 A/μs, V <sub>R</sub> = 30 V | -    | -    | 35   | ns    |
|  |                  | I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>REC</sub> = 0.25 A    | -    | -    | 25   |       |
|  |                  | T <sub>J</sub> = 25 °C   | -    | 20   | -    |       |
|  |                  | T <sub>J</sub> = 125 °C  | -    | 34   | -    |       |
| Peak recovery current  | I <sub>RPM</sub> | T <sub>J</sub> = 25 °C   | -    | 1.7  | -    | A     |
|  |                  | T <sub>J</sub> = 125 °C  | -    | 4.2  | -    |       |
| Reverse recovery charge  | Q <sub>rr</sub>  | T <sub>J</sub> = 25 °C   | -    | 23   | -    | nC    |
|  |                  | T <sub>J</sub> = 125 °C  | -    | 75   | -    |       |

| THERMAL - MECHANICAL SPECIFICATIONS            |                                   |   |              |      |            |                        |
|--|-----------------------------------|---|--------------|------|------------|------------------------|
| PARAMETER                                      | SYMBOL                            | TEST CONDITIONS                             | MIN.         | TYP. | MAX.       | UNITS                  |
| Maximum junction and storage temperature range | T <sub>J</sub> , T <sub>Stg</sub> |   | -55          | -    | 175        | °C                     |
| Thermal resistance, junction to case           | R <sub>thJC</sub>                 |   | -            | -    | 3.0        | °C/W                   |
| Thermal resistance, junction to ambient        | R <sub>thJA</sub>                 |   | -            | -    | 50         |                        |
| Thermal resistance, case to heatsink           | R <sub>thCS</sub>                 | Mounting surface, flat, smooth, and greased | -            | 0.5  | -          |                        |
| Weight   |                                   |   | -            | 2.0  | -          | g                      |
| Mounting torque                                |                                   |   | 6.0<br>(5.0) | -    | 12<br>(10) | kgf · cm<br>(lbf · in) |
| Marking device                                 |                                   | Case style D <sup>2</sup> PAK (TO-263AB)    | MURB820H     |      |            |                        |
|  |                                   | Case style TO-262AA                         | MURB820-1H   |      |            |                        |

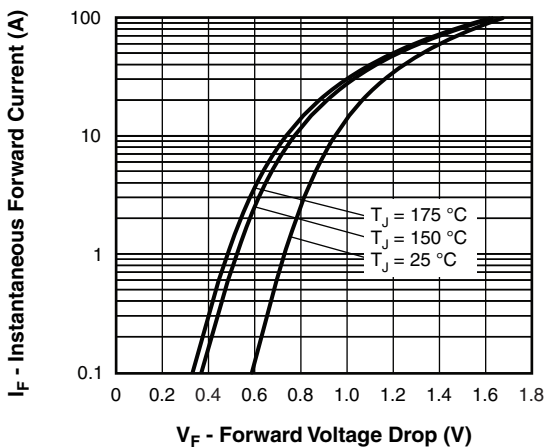


Fig. 1 - Typical Forward Voltage Drop Characteristics

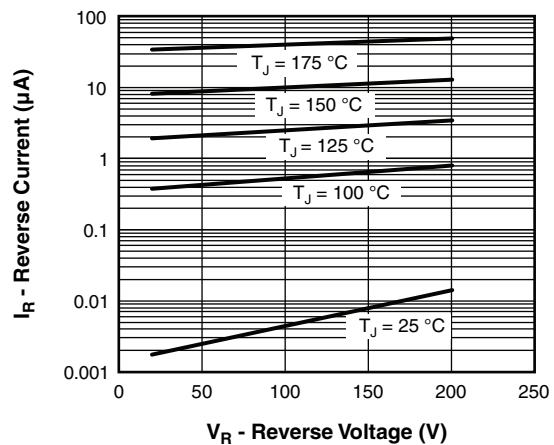


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

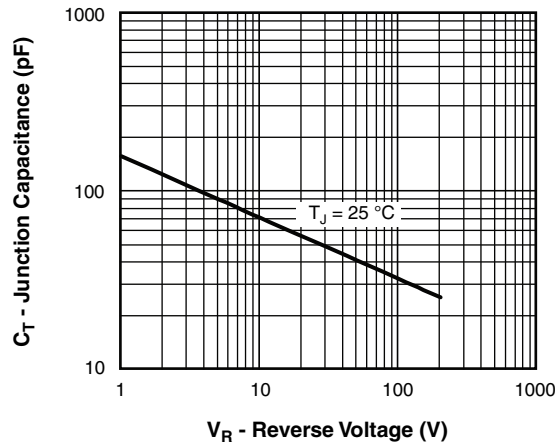


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

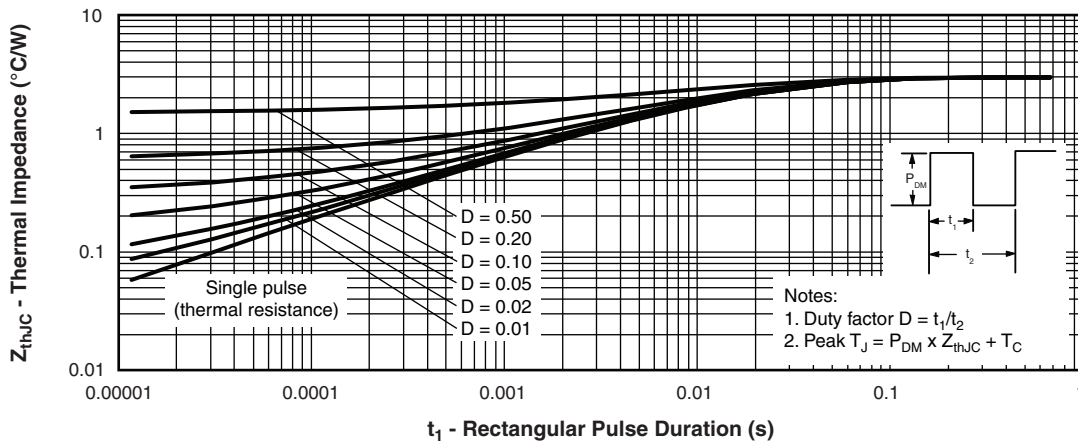


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

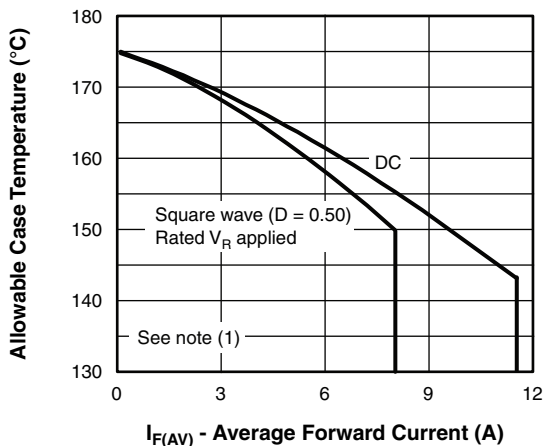


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

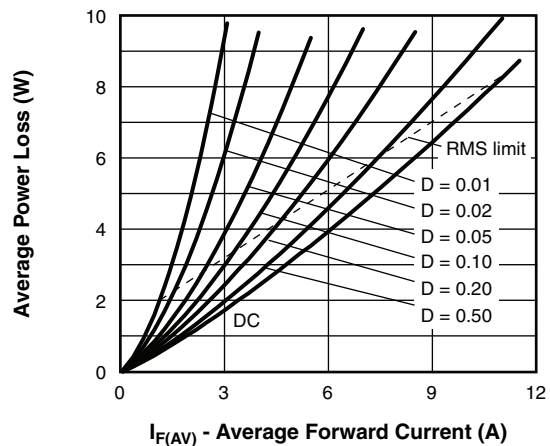


Fig. 6 - Forward Power Loss Characteristics

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{d_{REV}}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

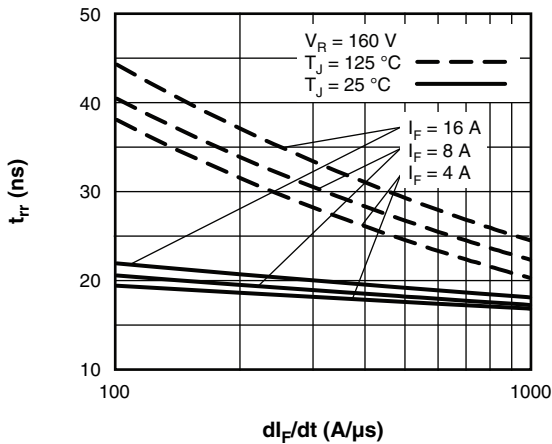


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$

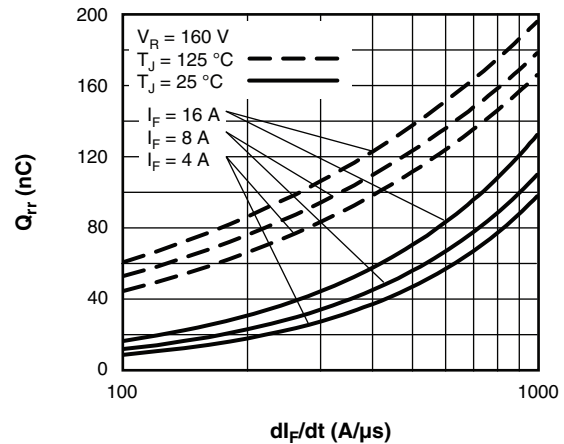
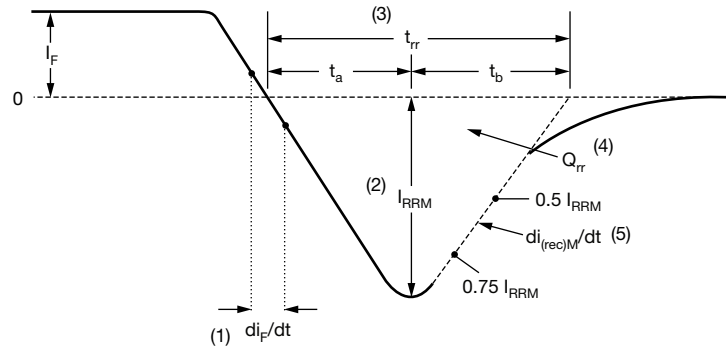


Fig. 8 - Typical Stored Charge vs.  $di_F/dt$



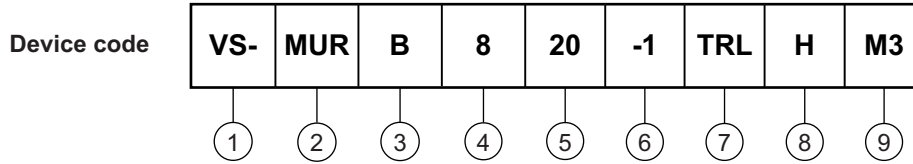
- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 9 - Reverse Recovery Waveform and Definitions



## ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Ultrafast MUR series
- 3** - B = D<sup>2</sup>PAK/TO-262
- 4** - Current rating (8 = 8 A)
- 5** - Voltage rating (20 = 200 V)
- 6** -
  - None = D<sup>2</sup>PAK
  - -1 = TO-262
- 7** -
  - None = tube (50 pieces)
  - TRL = tape and reel (left oriented, for D<sup>2</sup>PAK package only)
  - TRR = tape and reel (right oriented, for D<sup>2</sup>PAK package only)
- 8** - H = AEC-Q101 qualified
- 9** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

| ORDERING INFORMATION |               |                         |
|----------------------|---------------|-------------------------|
| PREFERRED P/N        | BASE QUANTITY | PACKAGING DESCRIPTION   |
| VS-MURB820HM3        | 50            | Antistatic plastic tube |
| VS-MURB820TRRHM3     | 800           | 13" diameter reel       |
| VS-MURB820TRLHM3     | 800           | 13" diameter reel       |
| VS-MURB820-1HM3      | 50            | Antistatic plastic tube |

| LINKS TO RELATED DOCUMENTS |                               |  |
|----------------------------|-------------------------------|--|
| Dimensions                 | D <sup>2</sup> PAK (TO-263AB) | <a href="http://www.vishay.com/doc?95046">www.vishay.com/doc?95046</a> |
|                            | TO-262AA                      | <a href="http://www.vishay.com/doc?95419">www.vishay.com/doc?95419</a> |
| Part marking information   | D <sup>2</sup> PAK (TO-263AB) | <a href="http://www.vishay.com/doc?95444">www.vishay.com/doc?95444</a> |
|                            | TO-262AA                      | <a href="http://www.vishay.com/doc?95443">www.vishay.com/doc?95443</a> |
| Packaging information      |                               | <a href="http://www.vishay.com/doc?95032">www.vishay.com/doc?95032</a> |
| SPIICE model               |                               | <a href="http://www.vishay.com/doc?96995">www.vishay.com/doc?96995</a> |

## D<sup>2</sup>PAK

### DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)



| SYMBOL | MILLIMETERS |       | INCHES |       | NOTES | SYMBOL | MILLIMETERS |       | INCHES    |       | NOTES |
|--------|-------------|-------|--------|-------|-------|--------|-------------|-------|-----------|-------|-------|
|        | MIN.        | MAX.  | MIN.   | MAX.  |       |        | MIN.        | MAX.  | MIN.      | MAX.  |       |
| A      | 4.06        | 4.83  | 0.160  | 0.190 |       | D1     | 6.86        | 8.00  | 0.270     | 0.315 | 3     |
| A1     | 0.00        | 0.254 | 0.000  | 0.010 |       | E      | 9.65        | 10.67 | 0.380     | 0.420 | 2, 3  |
| b      | 0.51        | 0.99  | 0.020  | 0.039 |       | E1     | 7.90        | 8.80  | 0.311     | 0.346 | 3     |
| b1     | 0.51        | 0.89  | 0.020  | 0.035 | 4     | e      | 2.54 BSC    |       | 0.100 BSC |       |       |
| b2     | 1.14        | 1.78  | 0.045  | 0.070 |       | H      | 14.61       | 15.88 | 0.575     | 0.625 |       |
| b3     | 1.14        | 1.73  | 0.045  | 0.068 | 4     | L      | 1.78        | 2.79  | 0.070     | 0.110 |       |
| c      | 0.38        | 0.74  | 0.015  | 0.029 |       | L1     | -           | 1.65  | -         | 0.066 | 3     |
| c1     | 0.38        | 0.58  | 0.015  | 0.023 | 4     | L2     | 1.27        | 1.78  | 0.050     | 0.070 |       |
| c2     | 1.14        | 1.65  | 0.045  | 0.065 |       | L3     | 0.25 BSC    |       | 0.010 BSC |       |       |
| D      | 8.51        | 9.65  | 0.335  | 0.380 | 2     | L4     | 4.78        | 5.28  | 0.188     | 0.208 |       |

#### Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB

## TO-262

**DIMENSIONS** in millimeters and inches

Modified JEDEC® outline TO-262



$\oplus 0.010 \text{ M} \text{ A} \text{ M} \text{ B}$



**Lead assignments**

- Diodes**  
 1. - Anode (two die)/open (one die)  
 2., 4. - Cathode  
 3. - Anode



| SYMBOL | MILLIMETERS |       | INCHES    |       | NOTES |
|--------|-------------|-------|-----------|-------|-------|
|        | MIN.        | MAX.  | MIN.      | MAX.  |       |
| A      | 4.06        | 4.83  | 0.160     | 0.190 |       |
| A1     | 2.03        | 3.02  | 0.080     | 0.119 |       |
| b      | 0.51        | 0.99  | 0.020     | 0.039 |       |
| b1     | 0.51        | 0.89  | 0.020     | 0.035 | 4     |
| b2     | 1.14        | 1.78  | 0.045     | 0.070 |       |
| b3     | 1.14        | 1.73  | 0.045     | 0.068 | 4     |
| c      | 0.38        | 0.74  | 0.015     | 0.029 |       |
| c1     | 0.38        | 0.58  | 0.015     | 0.023 | 4     |
| c2     | 1.14        | 1.65  | 0.045     | 0.065 |       |
| D      | 8.51        | 9.65  | 0.335     | 0.380 | 2     |
| D1     | 6.86        | 8.00  | 0.270     | 0.315 | 3     |
| E      | 9.65        | 10.67 | 0.380     | 0.420 | 2, 3  |
| E1     | 7.90        | 8.80  | 0.311     | 0.346 | 3     |
| e      | 2.54 BSC    |       | 0.100 BSC |       |       |
| L      | 13.46       | 14.10 | 0.530     | 0.555 |       |
| L1     | -           | 1.65  | -         | 0.065 | 3     |
| L2     | 3.36        | 3.71  | 0.132     | 0.146 |       |

**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline



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